



SPECIFICATION

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N : CL31A106MPHNNNE

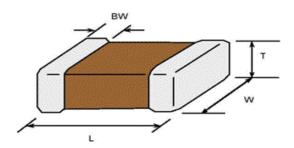
Product : Multi-layer Ceramic Capacitor Description : CAP, 10uF, 10V, ±20%, X5R, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>A</u> <u>106</u> <u>M</u> <u>P</u> <u>H</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> 1 2 3 4 5 6 7 8 9 10 11

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	1206 (inch code)	L: $3.20 \pm 0.20 \text{ mm}$	W:	$1.60 \pm 0.20 \text{ mm}$
(3)	Dielectric	X5R	Inner electrode		Ni
_	Capacitance	10 uF	Termination		Cu
<u>5</u>	Capacitance	±20 %	Plating		Sn 100% (Pb Free)
	tolerance		9 Product		Normal
6	Rated Voltage	10 V	Special		Reserved for future use
7	Thickness	1.60 ± 0.20 mm	① Packaging		Embossed Type, 7" reel

B. Structure & Dimension



Samsung P/N	Dimension(mm)				
Samsung F/N	L	W	Т	BW	
CL31A106MPHNNNE	3.20 ± 0.20	1.60 ± 0.20	1.60 ± 0.20	0.50 ± 0.30	

C. Samsung Reliablility Test and Judgement Condition

A capacitor prior to measuring the capacitance is heat treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours. Insulation		Judgement	Test condition		
Tan δ (DF) 0.05 max. treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours. Insulation 10,000Mohm or 100Mohm×μF Rated Voltage 60~120 sec. Resistance Whichever is smaller Rated Voltage 60~120 sec. Appearance No abnormal exterior appearance Microscope (×10) Withstanding No delectric breakdown or mechanical breakdown 250% of the rated voltage Temperature X5R (From-55°C to 85°C, Capacitance change should be within ±15%) Adhesive Strength No peeling shall be occur on the terminal electrode 500g·f, for 10±1 sec. Bending Strength Capacitance change: within ±12.5% Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface is to be soldered newly SnAg3.0Cu0.5 solder Solder ing Heat Tan δ, IR: initial spec. Solder pot: 270±5°C, 10±1sec. Resistance to Soldering Heat Capacitance change: within ±7.5% Solder pot: 270±5°C, 10±1sec. Wibration Test Capacitance change: within ±12.5% Amplitude: 1.5mm From 10Hz to 55Hz (return: 1min.) 2hours × 3 direction (x, y, z) Moisture Capacitance change: within ±12.5% With rated voltage Resistance Capacitance change: within ±12.5%	Capacitance	Within specified tolerance	1kHz ±10% / 1.0±0.2Vrms		
Resistance Whichever is smaller Microscope (×10) Appearance No abnormal exterior appearance Microscope (×10) Withstanding No dielectric breakdown 250% of the rated voltage Voltage mechanical breakdown Temperature X5R Characteristics (From-55°C to 85°C, Capacitance change should be within ±15%) Adhesive Strength No peeling shall be occur on the of Termination 500g·f, for 10±1 sec. Graminal electrode Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface is to be soldered newly SnAg3.0Cu0.5 solder 24±5°C, 3±0.3sec. Soldering Heat Tan 5, IR : initial spec. Solder pot : 270±5°C, 10±1 sec. Vibration Test Capacitance change : within ±7.5% Solder pot : 270±5°C, 10±1 sec. Moisture Capacitance change : within ±12.5% Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) Moisture Capacitance change : within ±12.5% With rated voltage Resistance Tan δ : 0.125 max With secondary is maller High Temperature Capacitance change : within ±12.5% With 150% of the rated voltage <th< th=""><th>Tan δ (DF)</th><th>0.05 max.</th><th>treated at 150 °C+0/-10 °C for 1 hour and maintained in</th></th<>	Tan δ (DF)	0.05 max.	treated at 150 °C+0/-10 °C for 1 hour and maintained in		
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Whichever is smaller High Temperature Capacitance change : within ±12.5% With 150% of the rated voltage Resistance Tan δ : 0.125 max Max. operating temperature IR : 1,000Mohm or 25Mohm × μ F 1,000+48/-0hrs Whichever is smaller Capacitance change : within ±7.5% 1 cycle condition Cycling Tan δ, IR : initial spec. Min. operating temperature → 25°C → Max. operating temperature → 25°C	Resistance	Tan δ: 0.125 max	40±2°C, 90~95%RH, 500+12/-0hrs		
Resistance Tan δ : 0.125 max Max. operating temperature IR : 1,000Mohm or 25Mohm × μ F 1,000+48/-0hrs Whichever is smaller 1 cycle condition Cycling Tan δ, IR : initial spec. Min. operating temperature Min. operating temperature → 25°C → Max. operating temperature → 25°C					
IR: 1,000Mohm or 25Mohm × μ F Whichever is smaller Temperature Cycling Capacitance change: within ±7.5% Tan δ , IR: initial spec. Min. operating temperature Max. operating temperature \rightarrow 25°C \rightarrow Max. operating temperature \rightarrow 25°C	High Temperature	Capacitance change: within ±12.5%	With 150% of the rated voltage		
	Resistance	Tan δ: 0.125 max	Max. operating temperature		
Cycling Tan δ, IR : initial spec. Min. operating temperature → 25°C → Max. operating temperature → 25°C			1,000+48/-0hrs		
→ Max. operating temperature → 25°C	Temperature	Capacitance change: within ±7.5%	1 cycle condition		
	Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C		
5 cycle test			ightarrow Max. operating temperature $ ightarrow$ 25°C		
			5 cycle test		

^{**} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260±5°C, 30sec.)



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

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- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- Any other applications with the same as or similar complexity or reliability to the applications set forth above.